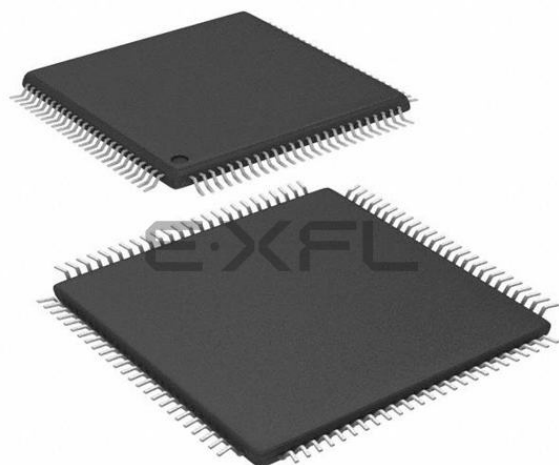




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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	85
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (12x12)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx320f128l-80i-pt

TABLE 2: PIC32MX USB – FEATURES

USB															
Device	Pins	Packages ⁽²⁾	MHz	Program Memory (KB)	Data Memory (KB)	Timers/Capture/Compare	Programmable DMA Channels	Dedicated USB DMA Channels	VREG	Trace	EUART/SPI/I ² C™	10-bit ADC (ch)	Comparators	PMP/PSP	JTAG
PIC32MX420F032H	64	PT, MR	40	32 + 12 ⁽¹⁾	8	5/5/5	0	2	Yes	No	2/1/2	16	2	Yes	Yes
PIC32MX440F128H	64	PT, MR	80	128 + 12 ⁽¹⁾	32	5/5/5	4	2	Yes	No	2/1/2	16	2	Yes	Yes
PIC32MX440F256H	64	PT, MR	80	256 + 12 ⁽¹⁾	32	5/5/5	4	2	Yes	No	2/1/2	16	2	Yes	Yes
PIC32MX440F512H	64	PT, MR	80	512 + 12 ⁽¹⁾	32	5/5/5	4	2	Yes	No	2/1/2	16	2	Yes	Yes
PIC32MX440F128L	100	PT	80	128 + 12 ⁽¹⁾	32	5/5/5	4	2	Yes	No	2/2/2	16	2	Yes	Yes
	121	BG													
PIC32MX460F256L	100	PT	80	256 + 12 ⁽¹⁾	32	5/5/5	4	2	Yes	Yes	2/2/2	16	2	Yes	Yes
	121	BG													
PIC32MX460F512L	100	PT	80	512 + 12 ⁽¹⁾	32	5/5/5	4	2	Yes	Yes	2/2/2	16	2	Yes	Yes
	121	BG													

Legend: PT = TQFP MR = QFN BG = XBGA

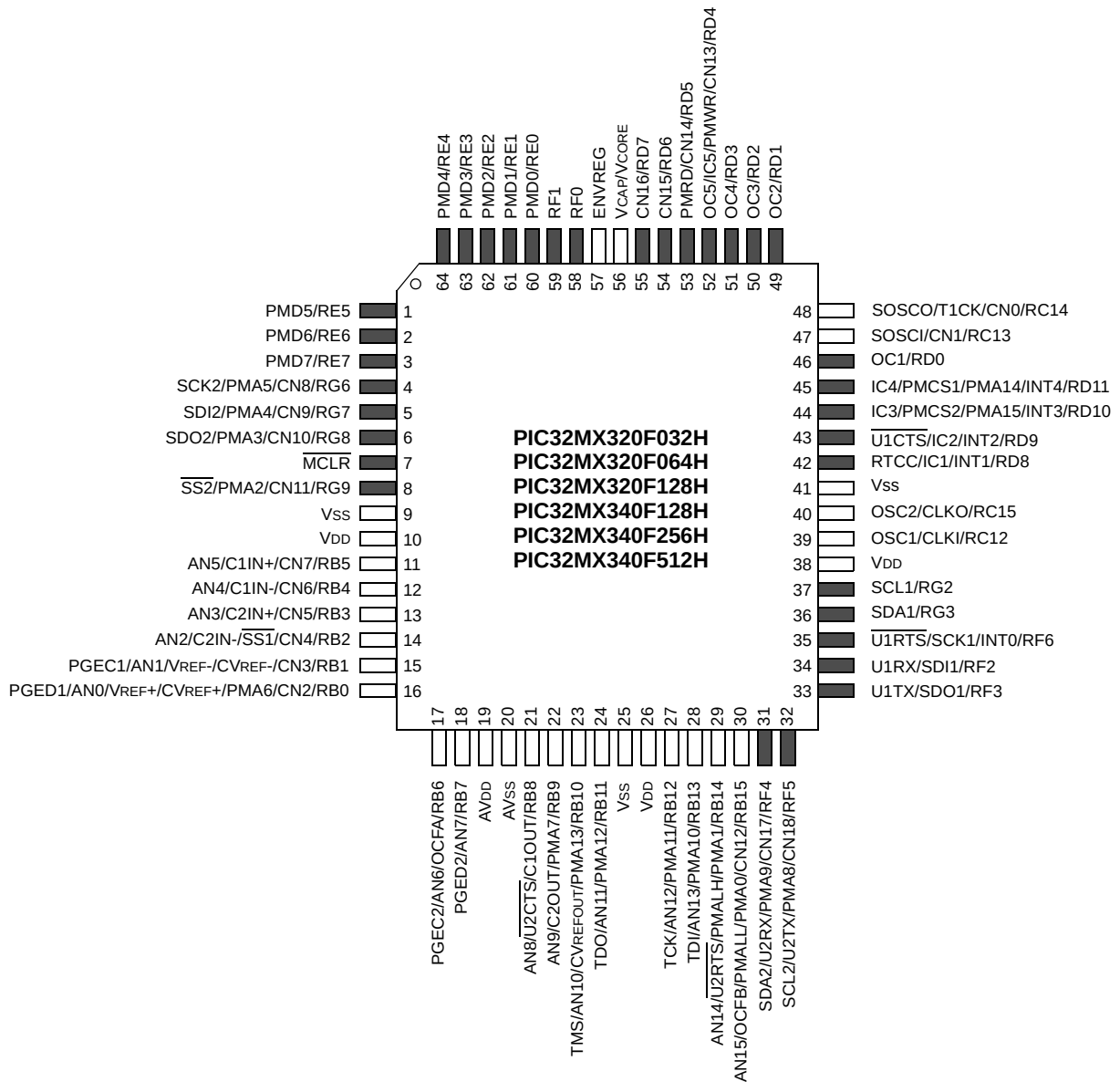
Note 1: This device features 12 KB Boot Flash memory.

2: See Legend for an explanation of the acronyms. See **Section 30.0 “Packaging Information”** for details.

Pin Diagrams (Continued)

64-Pin TQFP (General Purpose)

■ = Pins are up to 5V tolerant

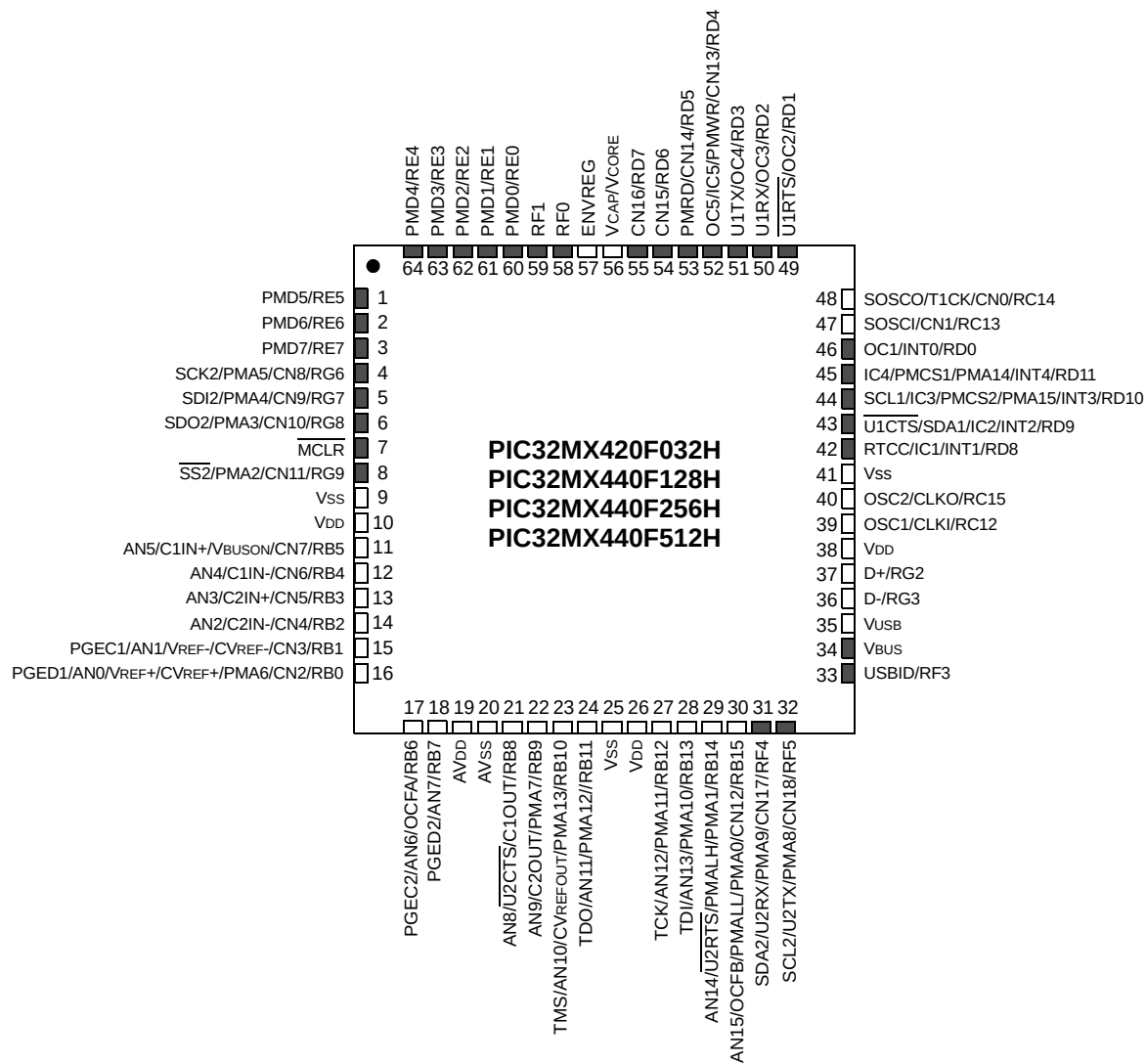


PIC32MX3XX/4XX

Pin Diagrams (Continued)

64-Pin QFN (USB)

■ = Pins are up to 5V tolerant



Note: The metal plane at the bottom of the device is not connected to any pins and is recommended to be connected to VSS externally.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number ⁽¹⁾			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
TMS	23	17	G3	I	ST	JTAG Test mode select pin.
TCK	27	38	J6	I	ST	JTAG test clock input pin.
TDI	28	60	G11	I	ST	JTAG test data input pin.
TDO	24	61	G9	O	—	JTAG test data output pin.
RTCC	42	68	E9	O	—	Real-Time Clock Alarm Output.
CVREF-	15	28	L2	I	Analog	Comparator Voltage Reference (low).
CVREF+	16	29	K3	I	Analog	Comparator Voltage Reference (high).
CVREFOUT	23	34	L5	O	Analog	Comparator Voltage Reference Output.
C1IN-	12	21	H2	I	Analog	Comparator 1 Negative Input.
C1IN+	11	20	H1	I	Analog	Comparator 1 Positive Input.
C1OUT	21	32	K4	O	—	Comparator 1 Output.
C2IN-	14	23	J2	I	Analog	Comparator 2 Negative Input.
C2IN+	13	22	J1	I	Analog	Comparator 2 Positive Input.
C2OUT	22	33	L4	O	—	Comparator 2 Output.
PMA0	30	44	L8	I/O	TTL/ST	Parallel Master Port Address Bit 0 Input (Buffered Slave modes) and Output (Master modes).
PMA1	29	43	K7	I/O	TTL/ST	Parallel Master Port Address Bit 1 Input (Buffered Slave modes) and Output (Master modes).
PMA2	8	14	F3	O	—	Parallel Master Port Address (De-multiplexed Master Modes).
PMA3	6	12	F2	O	—	
PMA4	5	11	F4	O	—	
PMA5	4	10	E3	O	—	
PMA6	16	29	K3	O	—	
PMA7	22	28	L2	O	—	
PMA8	32	50	L11	O	—	
PMA9	31	49	L10	O	—	
PMA10	28	42	L7	O	—	
PMA11	27	41	J7	O	—	
PMA12	24	35	J5	O	—	
PMA13	23	34	L5	O	—	
PMA14	45	71	C11	O	—	
PMA15	44	70	D11	O	—	
PMCS1	45	71	C11	O	—	Parallel Master Port Chip Select 1 Strobe.
PMCS2	44	70	D11	O	—	Parallel Master Port Chip Select 2 Strobe.

Legend: CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
TTL = TTL input buffer

Analog = Analog input P = Power
O = Output I = Input

Note 1: Pin numbers are provided for reference only. See the “Pin Diagrams” section for device pin availability.

TABLE 1-1: PINOUT I/O DESCRIPTIONS (CONTINUED)

Pin Name	Pin Number ⁽¹⁾			Pin Type	Buffer Type	Description
	64-pin QFN/TQFP	100-pin TQFP	121-pin XBGA			
PGED2	18	27	J3	I/O	ST	Data I/O pin for programming/debugging communication channel 2.
PGEC2	17	26	L1	I	ST	Clock input pin for programming/debugging communication channel 2.
MCLR	7	13	F1	I/P	ST	Master Clear (Reset) input. This pin is an active-low Reset to the device.
AVDD	19	30	J4	P	P	Positive supply for analog modules. This pin must be connected at all times.
AVSS	20	31	L3	P	P	Ground reference for analog modules.
VDD	10, 26, 38	2, 16, 37, 46, 62	C2, C9, E5, F8, G5, H4, H6, K8	P	—	Positive supply for peripheral logic and I/O pins.
VCORE/ VCAP	56	85	B7	P	—	Capacitor for Internal Voltage Regulator.
Vss	9, 25, 41	15, 36, 45, 65, 75	A8, B10, D4, D5, E7, F10, F5, G6, G7, H3	P	—	Ground reference for logic and I/O pins.
VREF+	16	29	K3	I	Analog	Analog voltage reference (high) input.
VREF-	15	28	L2	I	Analog	Analog voltage reference (low) input.

Legend: CMOS = CMOS compatible input or output Analog = Analog input P = Power
ST = Schmitt Trigger input with CMOS levels O = Output I = Input
TTL = TTL input buffer

Note 1: Pin numbers are provided for reference only. See the “Pin Diagrams” section for device pin availability.

2.0 GUIDELINES FOR GETTING STARTED WITH 32-BIT MICROCONTROLLERS

Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to the “PIC32 Family Reference Manual”, which is available from the Microchip web site (www.microchip.com/PIC32).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

2.1 Basic Connection Requirements

Getting started with the PIC32MX3XX/4XX family of 32-bit Microcontrollers (MCUs) requires attention to a minimal set of device pin connections before proceeding with development. The following is a list of pin names, which must always be connected:

- All VDD and VSS pins
(see **Section 2.2 “Decoupling Capacitors”**)
- All AVDD and AVSS pins (regardless if ADC module is not used)
(see **Section 2.2 “Decoupling Capacitors”**)
- VCAP/VCORE
(see **Section 2.3 “Capacitor on Internal Voltage Regulator (VCAP/VCORE)”**)
- MCLR pin
(see **Section 2.4 “Master Clear (MCLR) Pin”**)
- PGECx/PGEDx pins used for In-Circuit Serial Programming™ (ICSP™) and debugging purposes
(see **Section 2.5 “ICSP Pins”**)
- OSC1 and OSC2 pins when external oscillator source is used
(see **Section 2.8 “External Oscillator Pins”**)

Additionally, the following pins may be required:

- VREF+/VREF- pins used when external voltage reference for ADC module is implemented

Note: The AVDD and AVSS pins must be connected independent of ADC use and ADC voltage reference source.

2.2 Decoupling Capacitors

The use of decoupling capacitors on every pair of power supply pins, such as VDD, VSS, AVDD and AVSS is required. See Figure 2-1.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** Recommendation of 0.1 μ F (100 nF), 10-20V. This capacitor should be a low-ESR and have resonance frequency in the range of 20 MHz and higher. It is recommended that ceramic capacitors be used.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is within one-quarter inch (6 mm) in length.
- **Handling high frequency noise:** If the board is experiencing high frequency noise, upward of tens of MHz, add a second ceramic-type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 μ F to 0.001 μ F. Place this second capacitor next to the primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible. For example, 0.1 μ F in parallel with 0.001 μ F.
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum thereby reducing PCB track inductance.

2.9 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 2, ICD 3 or REAL ICE is selected as a debugger, it automatically initializes all of the Analog-to-Digital input pins (ANx) as “digital” pins by setting all bits in the ADPCFG register.

The bits in this register that correspond to the Analog-to-Digital pins that are initialized by MPLAB ICD 2, ICD 3 or REAL ICE, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain Analog-to-Digital pins as analog input pins during the debug session, the user application must clear the corresponding bits in the ADPCFG register during initialization of the ADC module.

When MPLAB ICD 2, ICD 3 or REAL ICE is used as a programmer, the user application firmware must correctly configure the ADPCFG register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all Analog-to-Digital pins being recognized as analog input pins, resulting in the port value being read as a logic ‘0’, which may affect user application functionality.

2.10 Unused I/Os

Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternately, inputs can be reserved by connecting the pin to Vss through a 1k to 10k resistor and configuring the pin as an input.

TABLE 4-3: INTERRUPT REGISTERS MAP FOR PIC32MX340F128H, PIC32MX340F256H, PIC32MX340F512H, PIC32MX340F128L, PIC32MX360F256L AND PIC32MX360F512L DEVICES ONLY⁽¹⁾

Virtual Address (BF88..#)	Register Name	Bit Range	Bits																All Resets	
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0		
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000	
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000	
1010	INTSTAT ⁽²⁾	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000	
1020	IPTMR	31:16	IPTMR<31:0>																0000	
		15:0																	0000	
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	SPI1RXIF	SPI1TXIF	SPI1EIF	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000	
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000	
1040	IFS1	31:16	—	—	—	—	—	—	—	FCEIF	—	—	—	—	DMA3IF	DMA2IF	DMA1IF	DMA0IF	0000	
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMP1IF	AD1IF	CNIF	0000	
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	SPI1RXIE	SPI1TXIE	SPI1EIE	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000	
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000	
1070	IEC1	31:16	—	—	—	—	—	—	—	FCEIE	—	—	—	—	DMA3IE	DMA2IE	DMA1IE	DMA0IE	0000	
		15:0	RTCCIE	FSCMIE	I2C2MIE	—	—	—	—	—	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMP1IE	AD1IE	CNIE	0000	
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>			—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>			—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>			—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>			—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>			—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>			—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>			—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>			—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>			—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>			—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	SPI1IP<2:0>			SPI1IS<1:0>			—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>			—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>			—	—	—	CNIP<2:0>			CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>			—	—	—	U1IP<2:0>			U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>			—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>			—	—	—	PMP1IP<2:0>			PMP1IS<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>			—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>			—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1120	IPC9	31:16	—	—	—	DMA3IP<2:0>			DMA3IS<1:0>			—	—	—	DMA2IP<2:0>			DMA2IS<1:0>		0000
		15:0	—	—	—	DMA1IP<2:0>			DMA1IS<1:0>			—	—	—	DMA0IP<2:0>			DMA0IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000	
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

- Note 1:** Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.
- 2:** This register does not have associated CLR, SET, and INV registers.

TABLE 4-37: PARALLEL MASTER PORT REGISTERS MAP⁽¹⁾

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
7000	PMCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	ADRMUX<1:0>		PMPCTL	PTWREN	PTRDEN	CSF<1:0>		ALP	CS2P	CS1P	—	WRSP	RDSP	0000
7010	PMMODE	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	BUSY	IRQM<1:0>		INCM<1:0>		MODE16	MODE<1:0>		WAITB<1:0>		WAITM<3:0>			WAITE<1:0>			0000
7020	PMADDR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	CS2EN/A15	CS1EN/A14	ADDR<13:0>														
7030	PMDOUT	31:16	DATAOUT<31:0>																0000
		15:0																	0000
7040	PMDIN	31:16	DATAIN<31:0>																0000
		15:0																	0000
7050	PMAEN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	PTEN<15:0>																0000
7060	PMSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	IBF	IBOV	—	—	IB3F	IB2F	IB1F	IB0F	OBE	OBUF	—	—	OB3E	OB2E	OB1E	OB0E	008F

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 “CLR, SET and INV Registers”** for more information.

TABLE 4-38: PROGRAMMING AND DIAGNOSTICS REGISTERS MAP

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
F200	DDPCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	JTAGEN	TROEN	—	—	0008

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

PIC32MX3XX/4XX

NOTES:

PIC32MX3XX/4XX

NOTES:

REGISTER 26-2: DEVCFG1: DEVICE CONFIGURATION WORD 1

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
23:16	R/P	r-1	r-1	R/P	R/P	R/P	R/P	R/P
	FWDTEN	—	—	WDTPS<4:0>				
15:8	R/P	R/P	R/P	R/P	r-1	R/P	R/P	R/P
	FCKSM<1:0>		FPBDIV<1:0>		—	OSCIOFNC	POSCMOD<1:0>	
7:0	R/P	r-1	R/P	r-1	r-1	R/P	R/P	R/P
	IESO	—	FSOSCEN	—	—	FNOSC<2:0>		

Legend:

R = Readable bit W = Writable bit P = Programmable bit r = Reserved bit
U = Unimplemented bit -n = Bit Value at POR: ('0', '1', x = Unknown)

bit 31-24 **Reserved:** Write '1'

bit 23 **FWDTEN:** Watchdog Timer Enable bit

1 = The WDT is enabled and cannot be disabled by software
0 = The WDT is not enabled; it can be enabled in software

bit 22-21 **Reserved:** Write '1'

bit 20-16 **WDTPS<4:0>:** Watchdog Timer Postscale Select bits

10100 = 1:1048576
10011 = 1:524288
10010 = 1:262144
10001 = 1:131072
10000 = 1:65536
01111 = 1:32768
01110 = 1:16384
01101 = 1:8192
01100 = 1:4096
01011 = 1:2048
01010 = 1:1024
01001 = 1:512
01000 = 1:256
00111 = 1:128
00110 = 1:64
00101 = 1:32
00100 = 1:16
00011 = 1:8
00010 = 1:4
00001 = 1:2
00000 = 1:1

All other combinations not shown result in operation = '10100'

bit 15-14 **FCKSM<1:0>:** Clock Switching and Monitor Selection Configuration bits

1x = Clock switching is disabled, Fail-Safe Clock Monitor is disabled
01 = Clock switching is enabled, Fail-Safe Clock Monitor is disabled
00 = Clock switching is enabled, Fail-Safe Clock Monitor is enabled

Note 1: Do not disable Posc (POSCMOD = 00) when using this oscillator source.

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REGISTER 26-4: DEVCFG3: DEVICE CONFIGURATION WORD 3

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
23:16	r-1	r-1	r-1	r-1	r-1	r-1	r-1	r-1
	—	—	—	—	—	—	—	—
15:8	R/P	R/P	R/P	R/P	R/P	R/P	R/P	R/P
	USERID<15:8>							
7:0	R/P	R/P	R/P	R/P	R/P	R/P	R/P	R/P
	USERID<7:0>							

Legend:

R = Readable bit W = Writable bit P = Programmable bit r = Reserved bit
U = Unimplemented bit -n = Bit Value at POR: ('0', '1', x = Unknown)

bit 31-16 **Reserved:** Write '1'

bit 15-0 **USERID<15:0>:** This is a 16-bit value that is user defined and is readable via ICSP™ and JTAG

REGISTER 26-5: DEVID: DEVICE AND REVISION ID REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R	R	R	R	R	R	R	R
	VER<3:0> ⁽¹⁾				DEVID<27:24> ⁽¹⁾			
23:16	R	R	R	R	R	R	R	R
	DEVID<23:16> ⁽¹⁾							
15:8	R	R	R	R	R	R	R	R
	DEVID<15:8> ⁽¹⁾							
7:0	R	R	R	R	R	R	R	R
	DEVID<7:0> ⁽¹⁾							

Legend:

R = Readable bit W = Writable bit P = Programmable bit r = Reserved bit
U = Unimplemented bit -n = Bit Value at POR: ('0', '1', x = Unknown)

bit 31-28 **VER<3:0>:** Revision Identifier bits⁽¹⁾

bit 27-0 **DEVID<27:0>:** Device ID⁽¹⁾

Note 1: See the "PIC32MX Flash Programming Specification" (DS61145) for a list of Revision and Device ID values.

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TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

Instruction	Description	Function
RDPGPR	Read GPR from Previous Shadow Set	$Rt = SGPR[SRSCtl_{PSS}, Rd]$
ROTR	Rotate Word Right	$Rd = Rt_{sa-1..0} Rt_{31..sa}$
ROTRV	Rotate Word Right Variable	$Rd = Rt_{Rs-1..0} Rt_{31..Rs}$
SB	Store Byte	$(byte)Mem[Rs+offset] = Rt$
SC	Store Conditional Word	if $LL_{bit} = 1$ $mem[Rs+offset] = Rt$ $Rt = LL_{bit}$
SDBBP	Software Debug Break Point	Trap to SW Debug Handler
SEB	Sign-Extend Byte	$Rd = SignExtend(Rs-7..0)$
SEH	Sign-Extend Half	$Rd = SignExtend(Rs-15..0)$
SH	Store Half	$(half)Mem[Rs+offset] = Rt$
SLL	Shift Left Logical	$Rd = Rt \ll sa$
SLLV	Shift Left Logical Variable	$Rd = Rt \ll Rs[4:0]$
SLT	Set on Less Than	if $(int)Rs < (int)Rt$ $Rd = 1$ else $Rd = 0$
SLTI	Set on Less Than Immediate	if $(int)Rs < (int)Immed$ $Rt = 1$ else $Rt = 0$
SLTIU	Set on Less Than Immediate Unsigned	if $(uns)Rs < (uns)Immed$ $Rt = 1$ else $Rt = 0$
SLTU	Set on Less Than Unsigned	if $(uns)Rs < (uns)Immed$ $Rd = 1$ else $Rd = 0$
SRA	Shift Right Arithmetic	$Rd = (int)Rt \gg sa$
SRAV	Shift Right Arithmetic Variable	$Rd = (int)Rt \gg Rs[4:0]$
SRL	Shift Right Logical	$Rd = (uns)Rt \gg sa$
SRLV	Shift Right Logical Variable	$Rd = (uns)Rt \gg Rs[4:0]$
SSNOP	Superscalar Inhibit No Operation	NOP
SUB	Integer Subtract	$Rt = (int)Rs - (int)Rd$
SUBU	Unsigned Subtract	$Rt = (uns)Rs - (uns)Rd$
SW	Store Word	$Mem[Rs+offset] = Rt$
SWL	Store Word Left	$Mem[Rs+offset] = Rt$
SWR	Store Word Right	$Mem[Rs+offset] = Rt$
SYNC	Synchronize	Orders the cached coherent and uncached loads and stores for access to the shared memory
SYSCALL	System Call	SystemCallException
TEQ	Trap if Equal	if $Rs == Rt$ TrapException
TEQI	Trap if Equal Immediate	if $Rs == (int)Immed$ TrapException

Note 1: This instruction is deprecated and should not be used.

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FIGURE 29-5: EXTERNAL RESET TIMING CHARACTERISTICS

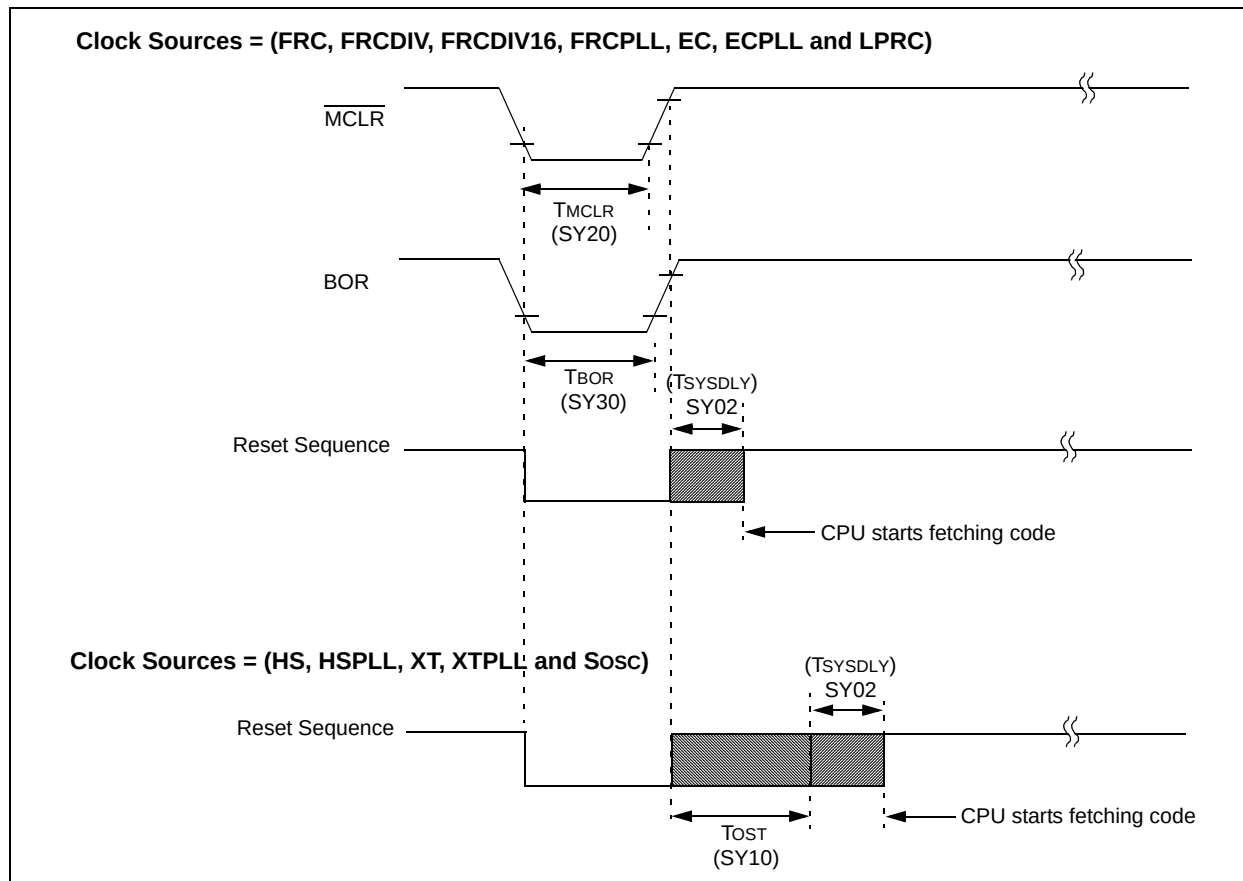


TABLE 29-22: RESETS TIMING

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typical ⁽²⁾	Max.	Units	Conditions
SY00	TPU	Power-up Period Internal Voltage Regulator Enabled	—	400	600	μs	-40°C to +85°C
SY01	TPWRT	Power-up Period External Vcore Applied (Power-Up-Timer Active)	48	64	80	ms	-40°C to +85°C
SY02	TSYSDLY	System Delay Period: Time required to reload Device Configuration Fuses plus SYSCLK delay before first instruction is fetched.	—	1 μs + 8 SYSCLK cycles	—	—	-40°C to +85°C
SY20	TMCLR	MCLR Pulse Width (low)	—	2	—	μs	-40°C to +85°C
SY30	TBOR	BOR Pulse Width (low)	—	1	—	μs	-40°C to +85°C

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, 25°C unless otherwise stated. Characterized by design but not tested.

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TABLE 29-40: OTG ELECTRICAL SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics ⁽¹⁾	Min.	Typ	Max.	Units	Conditions
USB313	VUSB	USB Voltage	3.0	—	3.6	V	Voltage on VUSB must be in this range for proper USB operation.
USB315	VILUSB	Input Low Voltage for USB Buffer	—	—	0.8	V	—
USB316	VIHUSB	Input High Voltage for USB Buffer	2.0	—	—	V	—
USB318	VDIFS	Differential Input Sensitivity	—	—	0.2	V	The difference between D+ and D- must exceed this value while VCM is met.
USB319	VCM	Differential Common Mode Range	0.8	—	2.5	V	—
USB320	ZOUT	Driver Output Impedance	28.0	—	44.0	Ω	—
USB321	VoL	Voltage Output Low	0.0	—	0.3	V	1.5 kΩ load connected to 3.6V.
USB322	VoH	Voltage Output High	2.8	—	3.6	V	1.5 kΩ load connected to ground.

Note 1: These parameters are characterized, but not tested in manufacturing.

FIGURE 29-23: EJTAG TIMING CHARACTERISTICS

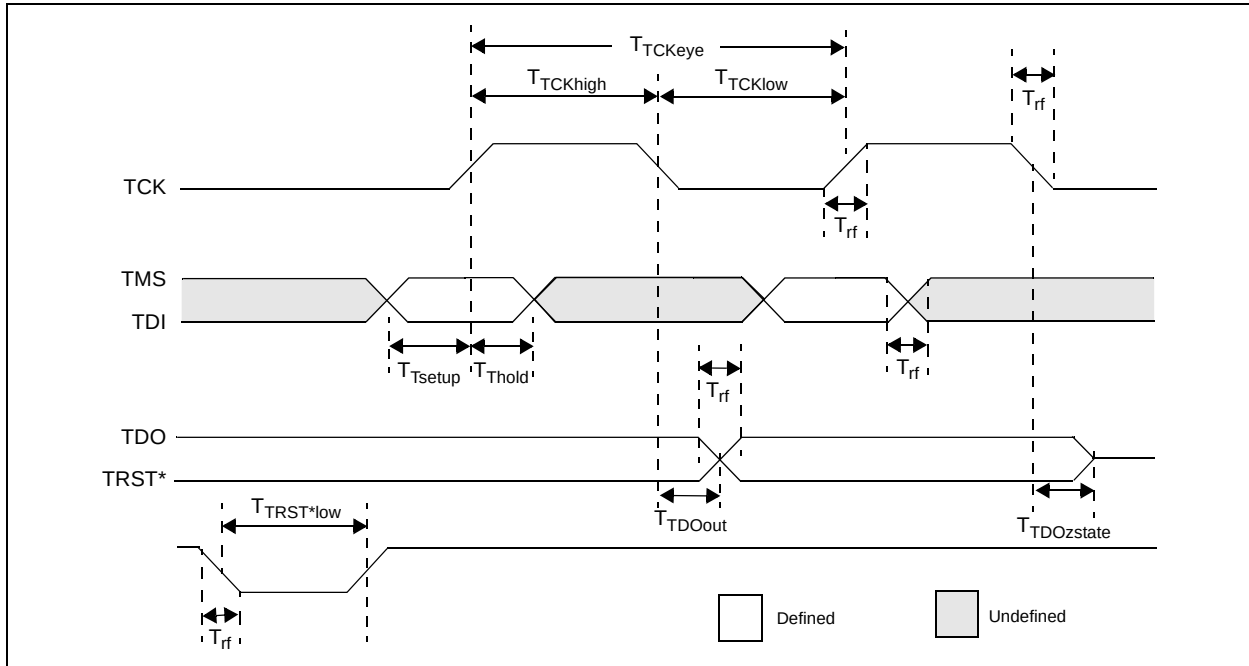


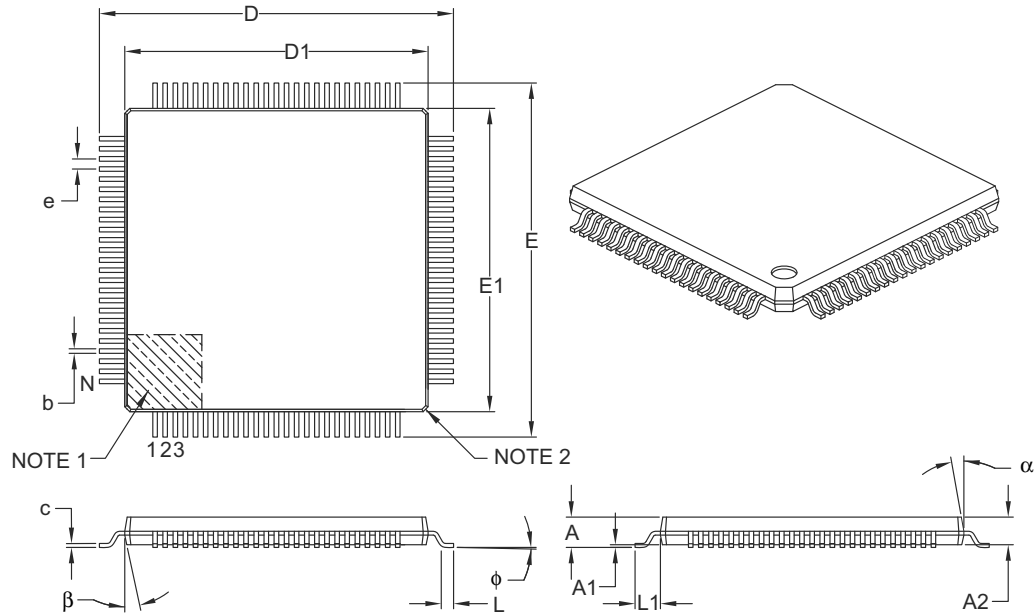
TABLE 29-41: EJTAG TIMING REQUIREMENTS

AC CHARACTERISTICS				Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp		
Param. No.	Symbol	Description ⁽¹⁾	Min.	Max.	Units	Conditions
EJ1	TTCKCYC	TCK Cycle Time	25	—	ns	—
EJ2	TTCKHIGH	TCK High Time	10	—	ns	—
EJ3	TTCKLOW	TCK Low Time	10	—	ns	—
EJ4	TTSETUP	TAP Signals Setup Time Before Rising TCK	5	—	ns	—
EJ5	TTHOLD	TAP Signals Hold Time After Rising TCK	3	—	ns	—
EJ6	TTDOOUT	TDO Output Delay Time from Falling TCK	—	5	ns	—
EJ7	TTDOZSTATE	TDO 3-State Delay Time from Falling TCK	—	5	ns	—
EJ8	TTRSTLOW	TRST Low Time	25	—	ns	—
EJ9	TRF	TAP Signals Rise/Fall Time, All Input and Output	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N	100		
Lead Pitch	e	0.40 BSC		
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1	1.00 REF		
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E	14.00 BSC		
Overall Length	D	14.00 BSC		
Molded Package Width	E1	12.00 BSC		
Molded Package Length	D1	12.00 BSC		
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
- Chamfers at corners are optional; size may vary.
- Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
- Dimensioning and tolerancing per ASME Y14.5M.

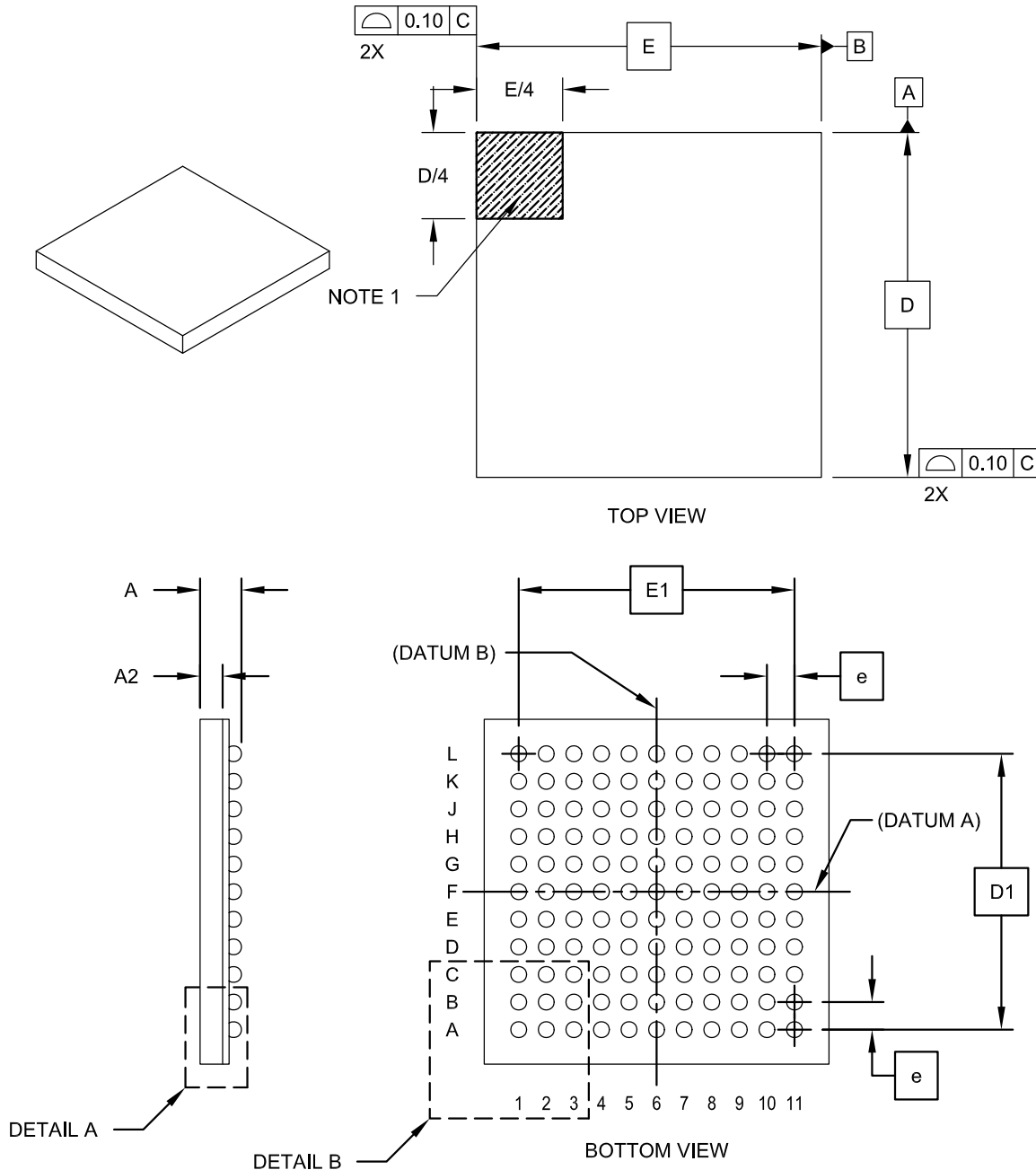
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B

121-Lead Plastic Thin Profile Ball Grid Array (BG) - 10x10x1.10 mm Body [XBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-148B Sheet 1 of 2

APPENDIX A: REVISION HISTORY

Revision E (July 2008)

- Updated the PIC32MX340F128H features in Table 1 to include 4 programmable DMA channels.

Revision F (June 2009)

This revision includes minor typographical and formatting changes throughout the data sheet text.

Global changes include:

- Changed all instances of OSCI to OSC1 and OSC0 to OSC2
- Changed all instances of VDDCORE and VDDCORE/VCAP to VCAP/VDDCORE
- Deleted registers in most sections, refer to the related section of the *"PIC32 Family Reference Manual"* (DS61132).

The other changes are referenced by their respective section in the following table.

TABLE A-1: MAJOR SECTION UPDATES

Section Name	Update Description
"High-Performance, General Purpose and USB 32-bit Flash Microcontrollers"	Added a "Packages" column to Table 1 and Table 2. Corrected all pin diagrams to update the following pin names. - Changed PGC1/EMUC1 to PGEC1 - Changed PGD1/EMUD1 to PGED1 - Changed PGC2/EMUC2 to PGEC2 - Changed PGD2/EMUD2 to PGED2 Shaded appropriate pins in each diagram to indicate which pins are 5V tolerant. Added 64-Lead QFN package pin diagrams, one for General Purpose and one for USB.
Section 1.0 "Device Overview"	Reconstructed Figure 1-1 to include Timers, ADC and RTCC in the block diagram.
Section 2.0 "Guidelines for Getting Started with 32-bit Microcontrollers"	Added a new section to the data sheet that provides the following information: - Basic Connection Requirements - Capacitors - Master Clear Pin - ICSP™ Pins - External Oscillator Pins - Configuration of Analog and Digital Pins - Unused I/Os
Section 4.0 "Memory Organization"	Updated the memory maps, Figure 4-1 through Figure 4-6. All summary peripheral register maps were relocated to Section 4.0 "Memory Organization".
Section 7.0 "Interrupt Controller"	Removed the "Address" column from Table 7-1.
Section 12.0 "I/O Ports"	Added a second paragraph in Section 12.1.3 "Analog Inputs" to clarify that all pins that share ANx functions are analog by default, because the AD1PCFG register has a default value of 0x0000.